



US00D513608S

(12) **United States Design Patent** (10) **Patent No.:** **US D513,608 S**
Harnden et al. (45) **Date of Patent:** **** Jan. 17, 2006**

(54) **PORTION OF A MATRIX FOR SURFACE MOUNT PACKAGE LEADFRAME**

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(**) Term: **14 Years**

(21) Appl. No.: **29/173,644**

(22) Filed: **Jan. 3, 2003**

(51) **LOC (8) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Classification Search** D13/182;
 29/622, 740, 827; 74/56.2, 52.4; 206/713,
 206/714, 715, 716, 727, 728; 257/667, 668;
 333/185; 428/573

See application file for complete search history.

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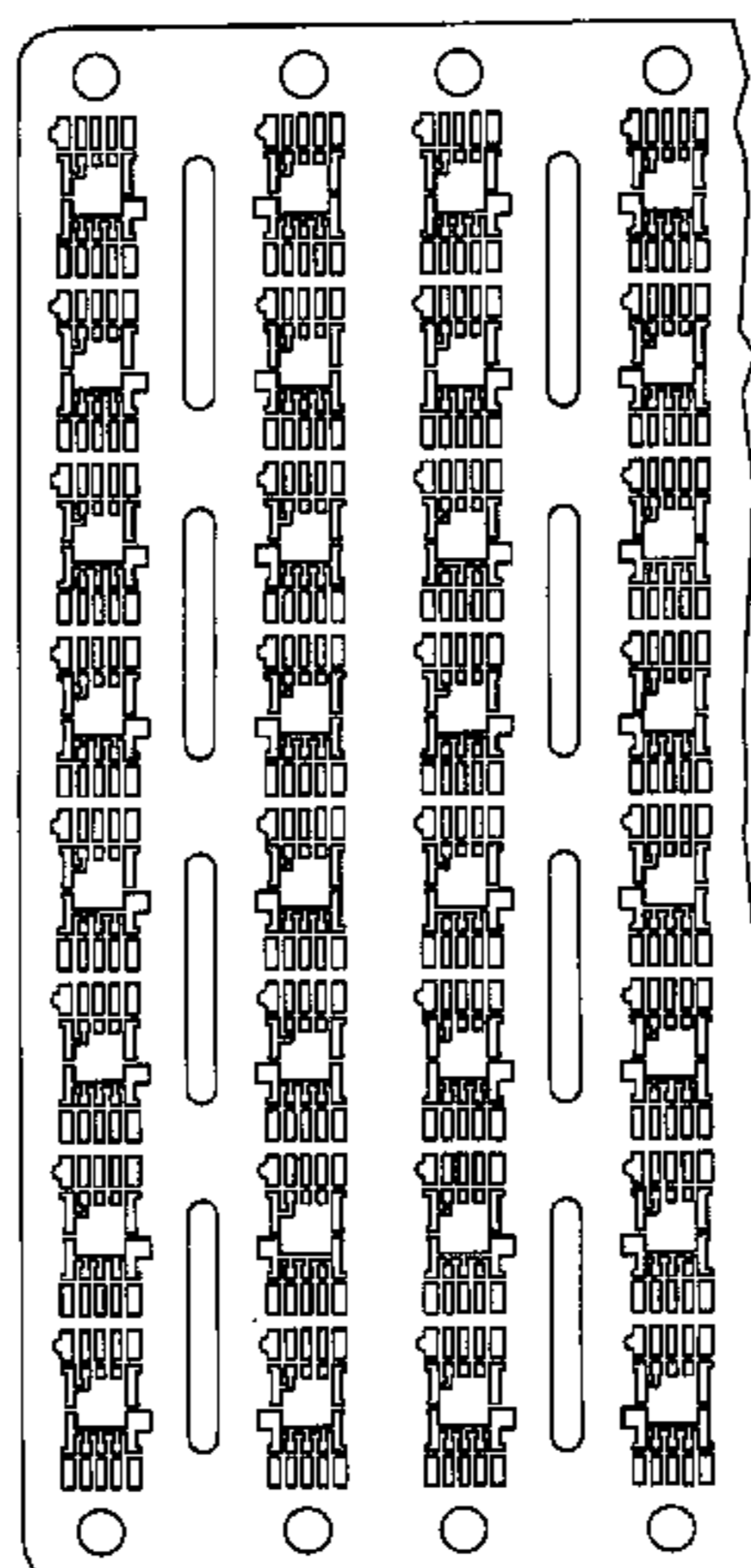
(57) **CLAIM**

The ornamental design for portion of a matrix for surface mount package leadframe, as shown and described.

DESCRIPTION

FIG. 1 is a top plan view of a portion of a matrix for surface mount package leadframe showing my new design;
 FIG. 2 is a top plan view of an enlarged fragment of the portion of a matrix for surface mount package leadframe; and,
 FIG. 3 is a perspective view of a portion of a matrix for surface mount package leadframe.

1 Claim, 3 Drawing Sheets



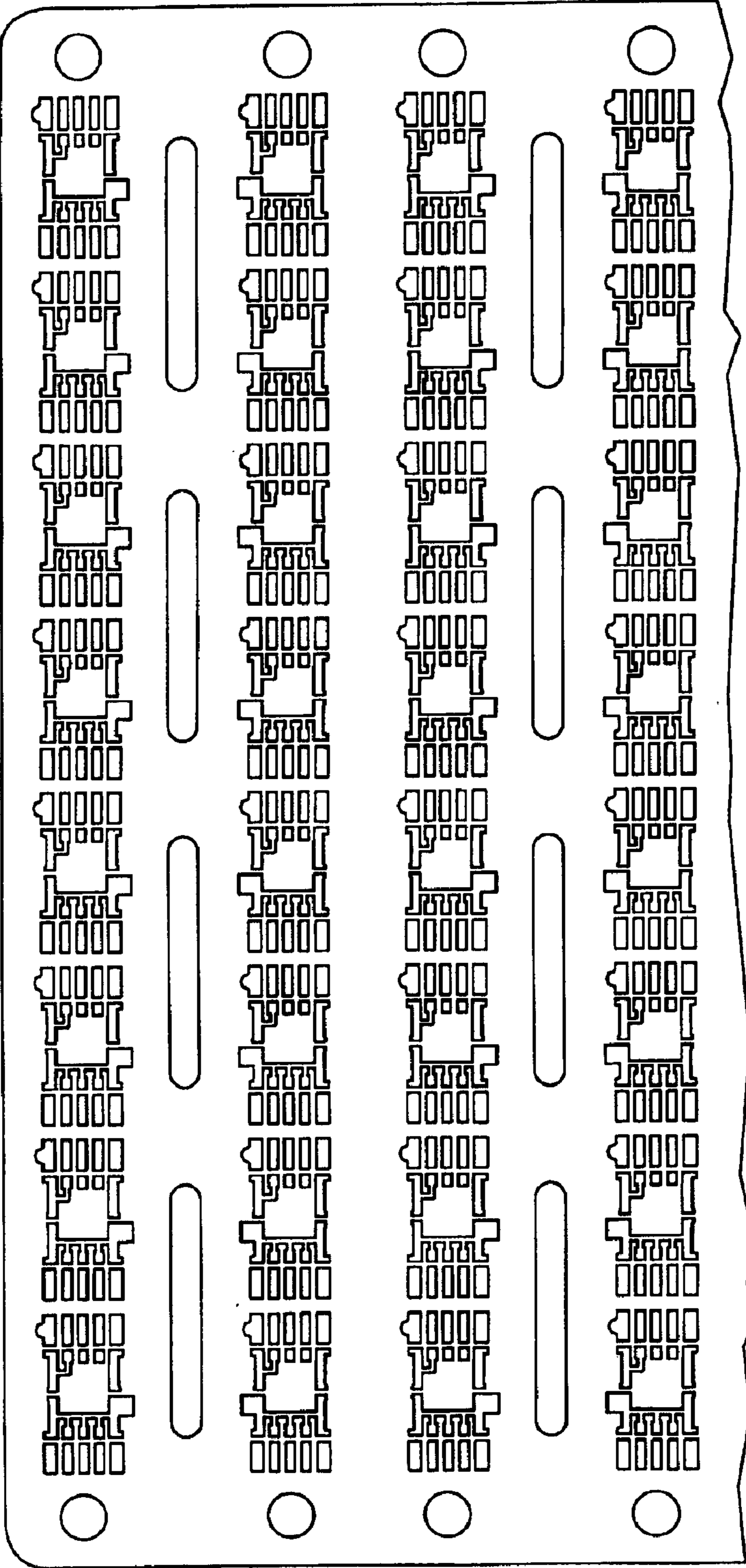


FIG. 1

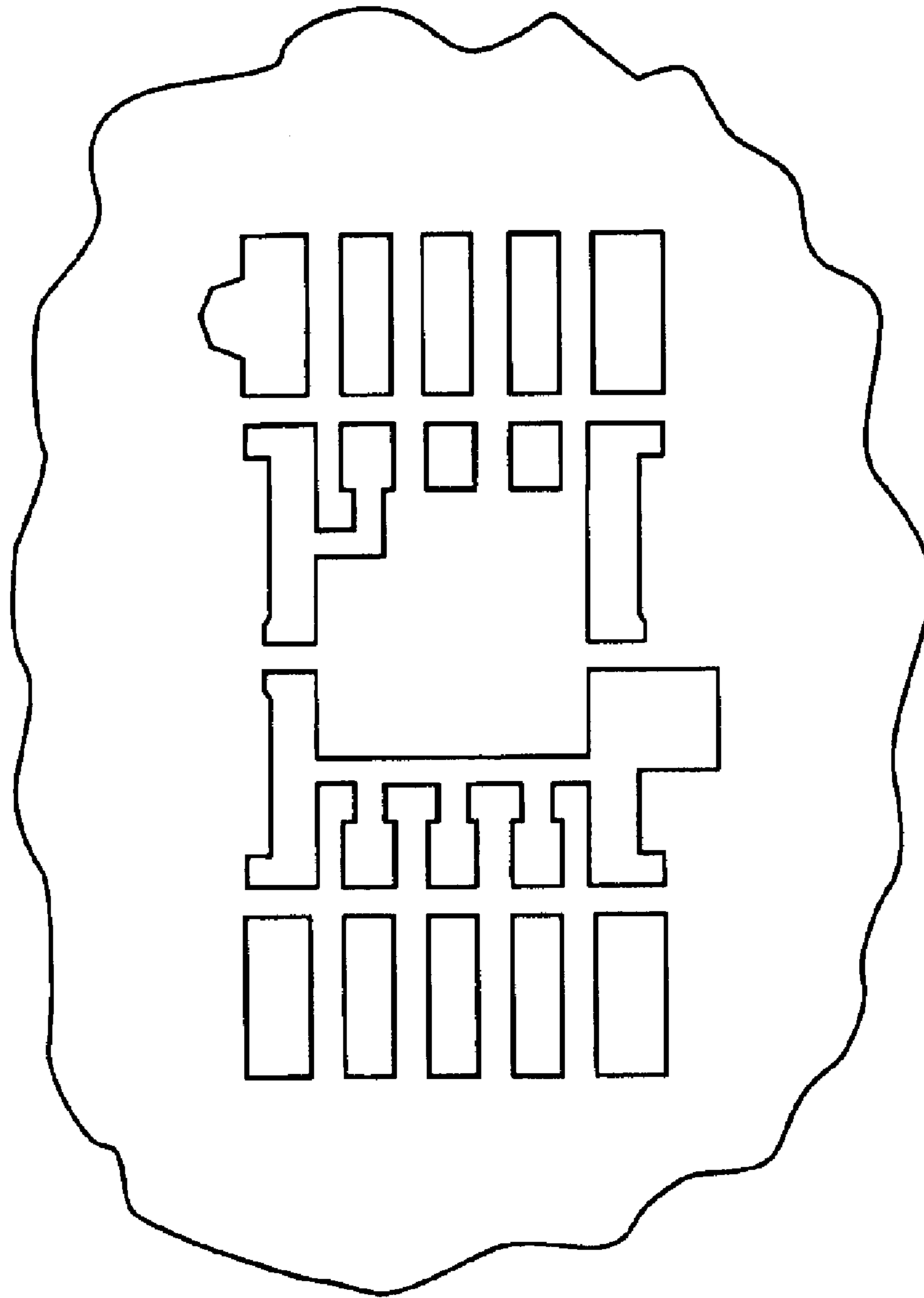


FIG. 2

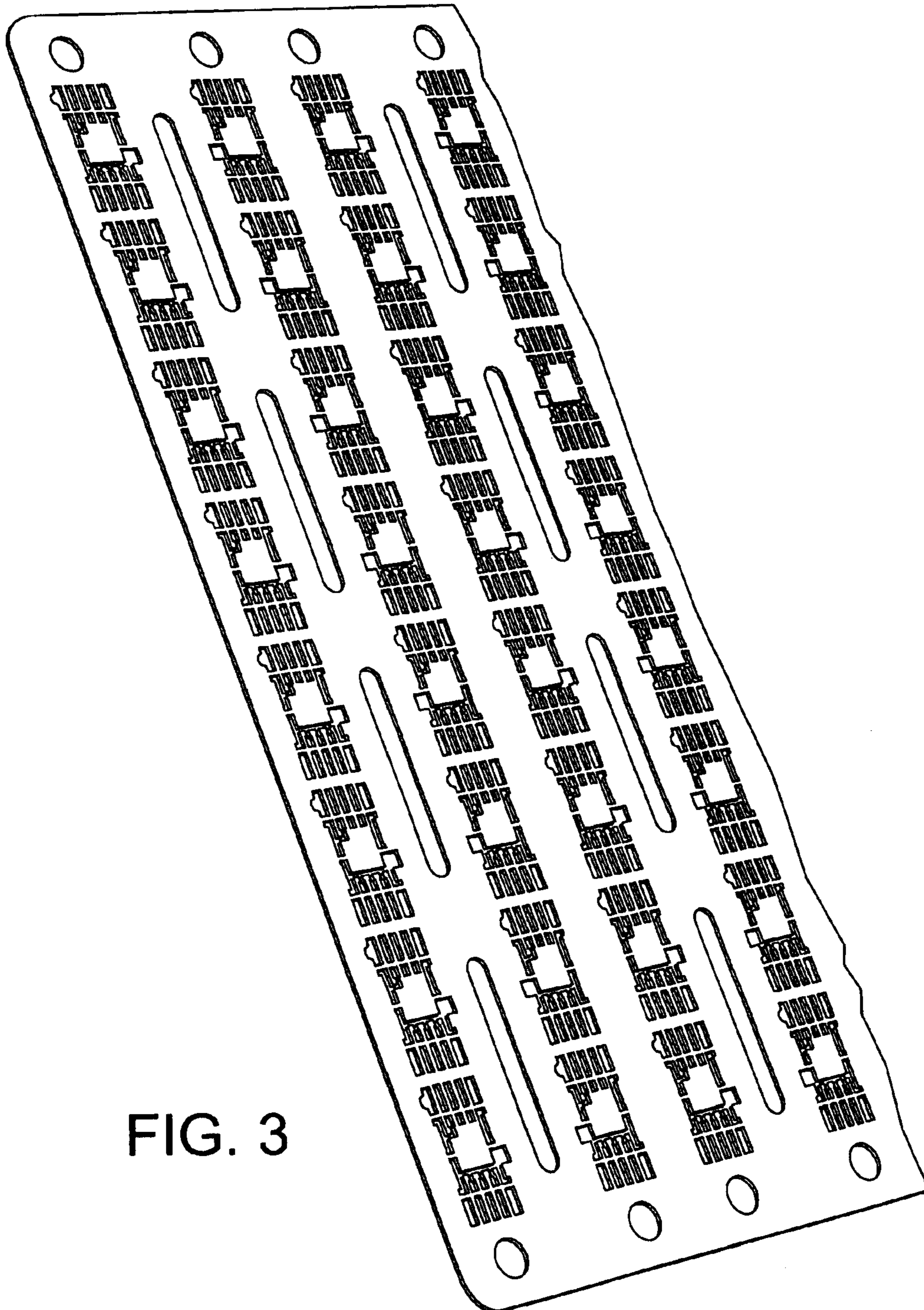


FIG. 3